

(1.27 mm) .050"

SEAM SERIES

# HIGH-SPEED/HIGH-DENSITY OPEN-PIN-FIELD

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?SEAM](http://www.samtec.com?SEAM)

### Insulator Material:

Black LCP

### Contact Material:

Copper Alloy

### Operating Temp Range:

-55 °C to +125 °C

### Current Rating

(7 mm stack height):

1.8 A per pin  
(10 adjacent pins powered)

### Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

### Working Voltage:

240 VAC

### RoHS Compliant:

Yes

### Lead-Free Solderable:

Yes

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

## STANDARDS

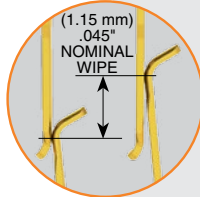
- VITA 47
- VITA 57.1 FMC
- VITA 57.4 FMC+
- VITA 74 VNX

## PROTOCOLS

- 100 GbE
- Fibre Channel
- Rapid I/O
- PCI Express®
- SATA
- InfiniBand™

Mates with:  
SEAF, SEAFP

Standoffs:  
JSO



Low  
insertion/  
extraction  
forces

Up to 500  
Pins



## HIGH-SPEED CHANNEL PERFORMANCE

SEAF/SEAM @ 10 mm Mated Stack Height

Rating based on Samtec reference channel.

For full SI performance data visit [Samtec.com](http://Samtec.com) or contact [SIG@samtec.com](mailto:SIG@samtec.com)

PAM 4

56

G b p s

## OTHER SOLUTIONS

- Up to 560 pins

Solder  
charges

SEAM — NO. PINS PER ROW — LEAD STYLE — PLATING OPTION — NO. OF ROWS — SOLDER TYPE — A — K — TR

–10, –15, –20,  
–30, –40, –50  
(–10 only available in 04 row)  
(–15 is only available in 4 Row  
with –02.0 lead style and 10  
row with any lead style)

Specify  
LEAD  
STYLE  
from  
chart

NO. OF ROWS	B
–04	(7.06) .278
–05, –06	(9.60) .378
–08	(12.14) .478
–10	(14.68) .578

–L  
= 10 μ"  
(0.25 μm)  
Gold on  
contact area,  
Matte Tin on  
solder tail

–S  
= 30 μ"  
(0.76 μm)  
Gold on  
contact area,  
Matte Tin on  
solder tail

–04  
= Four Rows  
(–06.5 not  
available)

–05  
= Five Rows  
(–06.5 not  
available)

–06  
= Six Rows  
(–06.5 not  
available)

–08  
= Eight Rows

–10  
= Ten Rows

–1  
= Tin/Lead Alloy  
Solder Charge

–2  
= Lead-Free  
Solder Charge

–A  
= Alignment Pins  
(Required. Arrays  
will not self-center  
on solder pads)

–K  
= Polyimide film  
Pick & Place Pad

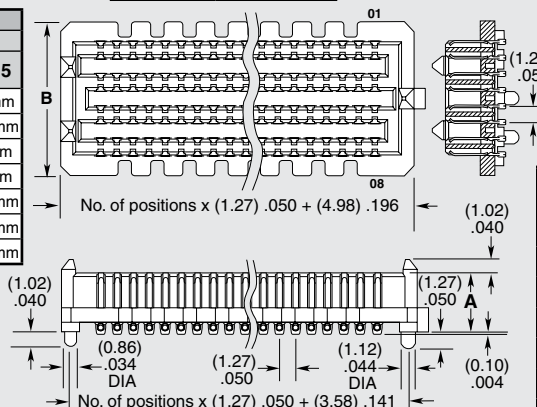
–TR  
= Tape & Reel

SEAM LEAD STYLE	MATED HEIGHTS SEAF LEAD STYLE			
	–05.0	–06.0	–06.5	–07.5
–02.0	7 mm	8 mm	8.5 mm	9.5 mm
–03.0	8 mm	9 mm	9.5 mm	10.5 mm
–03.5	8.5 mm	9.5 mm	10 mm	11 mm
–06.5	11.5 mm	12.5 mm	13 mm	14 mm
–07.0	12 mm	13 mm	13.5 mm	14.5 mm
–09.0	14 mm	15 mm	15.5 mm	16.5 mm
–11.0	16 mm	17 mm	17.5 mm	18.5 mm

Notes:  
Patented

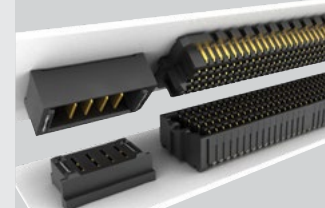
IPC-A-610F and  
IPC J-STD-001F Class 3  
solder joint.

Some sizes, styles and  
options are non-standard,  
non-returnable.



LEAD STYLE	A
–02.0	(4.60) .181
–03.0	(5.59) .220
–03.5	(6.10) .240
–06.5	(9.14) .360
–07.0	(9.60) .378
–09.0	(11.60) .457
–11.0	(13.60) .535

## POWER/SIGNAL APPLICATION



Compatible with  
UMPT/UMPS for flexible  
two-piece power/signal solutions

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.